

Customer No.: 31561
Application No.: 10605,034
Docket No.: 10231-US-PA

Amendment

FOR THE TITLE

Please amend the title of this application as "CHIP PACKAGE
STRUCTURE WITH STIFFENER AND METHOD FOR MANUFACTURING
THE SAME".

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IN THE SPECIFICATION

Paragraph [0017]

Figs. 2-8 Figures 2, 3 and 4-8 are cross-sectional views illustrating the manufacturing steps of the mini BGA package structure according to one preferred embodiment of the present invention.

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